



Title of Change:	SOD-123 devices Cu wire qualification at ON Semiconductor, Leshan, China facility.		
Proposed first ship date:	5 August 2015		
Contact information:	Contact your local ON Semiconductor Sales Office or <Coleen.Long@onsemi.com >		
Samples:	Contact your local ON Semiconductor Sales Office		
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <zz.cheng@onsemi.com >		
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <PCN.Support@onsemi.com>.		
Change Part Identification:	At the expiration of this FPCN devices will be assembled with Cu Wire at ON Semiconductor's existing Leshan facility. Devices with Cu Wire will have date code of WW31, 2015 or later.		
Change category(s):	<input type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Product specific change <input type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Assembly Change <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Test Change <input type="checkbox"/> Other: _____		
Sites Affected:	<u>Site 1</u>	<u>Site 2</u>	
<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : <input type="checkbox"/> External Foundry/Subcon site(s):	ON Leshan, China		
Description and Purpose:			
ON Semiconductor is pleased to announce the completion of Cu Wire qualification for the impacted devices at ON Semiconductor's Leshan, China facility. The impacted devices are currently assembled at the ON Semiconductor Leshan, China facility with Au Wire. At the expiration of this PCN, these devices will be built with Cu Wire at the same site. There is no change in package outline or electrical performance of the parts they continue to fully meet datasheet specifications.			
Reliability Data Summary:			
Qual vehicle :			
BAT54T1G			
Test	Condition	Interval	Results
HTRB	Tj=150C or operating Tj 80% V bias (JA108)	1008 Hrs	0/231
HTSL	Ta=150C, or 175C based on datasheet max TA storage	1008 Hrs	0/231
IOL	Ta=+25°C, deltaTj=100°C max, 2min on/off for 15000 cyc	15000 Cycle	0/231
TC	Temp = -65°C to +150°C; for 1000 cycles (JA104B)	1000 Cycle	0/231
AC	Temp = +121°C; RH =100%, (JA110)	96 Hrs	0/231
H3TRB	Temp = +85°C; RH = 85%, 80% V bias (JA101)	1008 Hrs	0/231
RSH	TS=260C, Tdwell=10 sec. (Jedec B-106)		0/90

**MMSD103T1G**

Test	Condition	Interval	Results
HTRB	Tj=150C or operating Tj 80% V bias (JA108)	1008 Hrs	0/231
HTSL	Ta=150C, or 175C based on datasheet max TA storage	1008 Hrs	0/231
IOL	Ta=+25°C, deltaTj=100°C max, 2min on/off for 15000 cyc	15000Cycle	0/231
TC	Temp = -65°C to +150°C; for 1000 cycles (JA104B)	1000 Cycle	0/231
AC	Temp = +121°C; RH =100%, (JA110)	96 Hrs	0/231
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RSH	TS=260C, Tdwell=10 sec. (Jedec B-106)		0/90

Electrical Characteristic Summary:

Electrical Characteristics are not impacted.

List of Affected Standard Parts:

MMSD301T1G
MMSD701T1G
MMSD4148T3G
MMSD4148T1G